

REVISION HISTORY

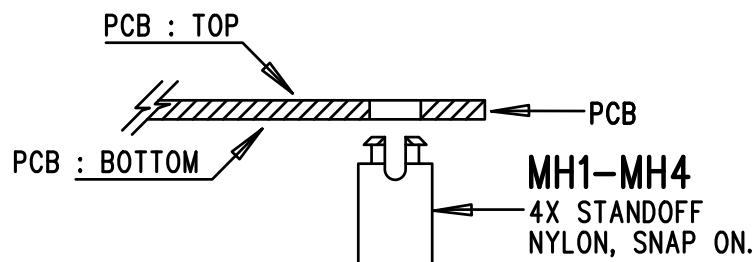
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	BOB S.	08-06-14

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. MARK EACH ASSEMBLY TYPE AND SUFFIX IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	SUFFIX
A	LTC4231-1	1
B	LTC4231-2	2

8. INSTALL 4 STANDOFFS AS SHOWN BELOW:



APPROVALS

PCB DES.	KIM T.
APP ENG.	BOB S.

SCALE = NONE



1630 MCCARTHY BLVD
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TITLE: TOP ASSEMBLY DRAWING

MICROPOWER HOT SWAP CONTROLLER

SIZE N/A	IC NO. LTC4231IMS-1/2 DEMO CIRCUIT 2161A	REV. 2
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FILENAME: DC2161A-2.PCB

SHT 1 OF 1